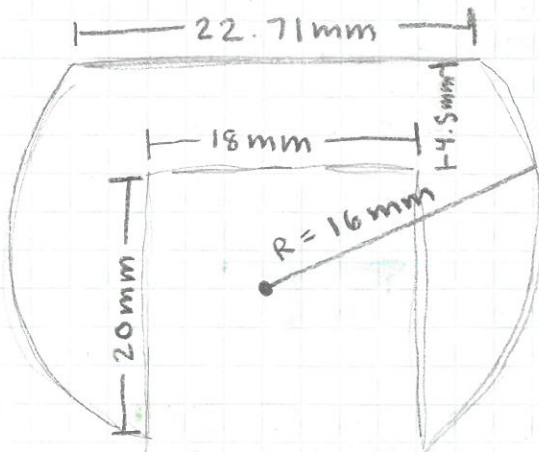
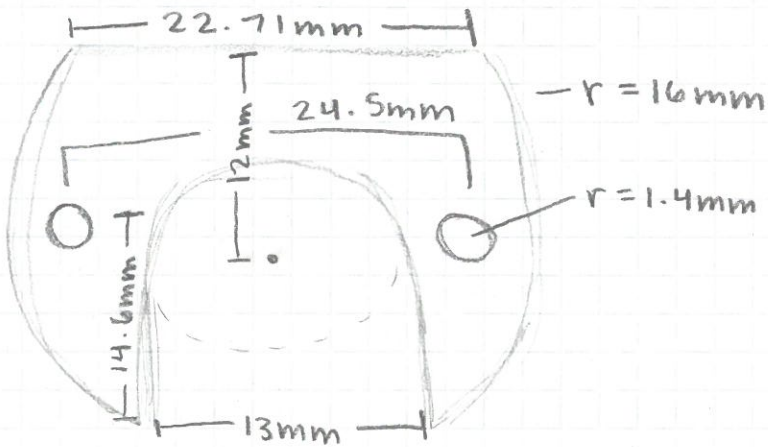


Sketch #1



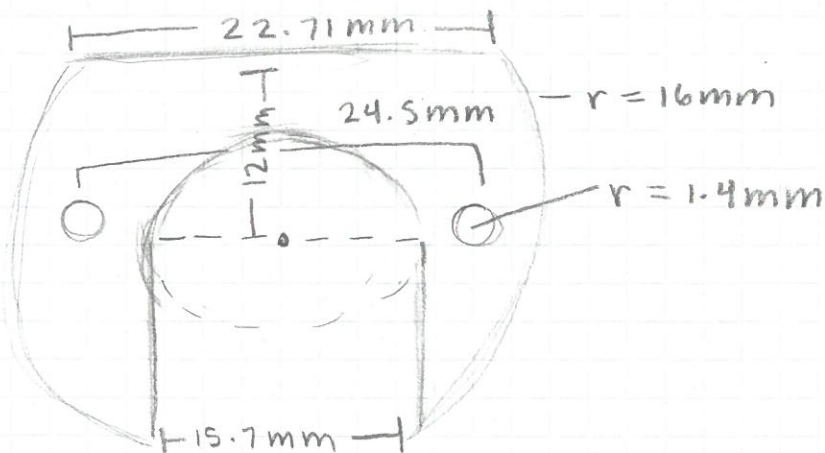
height = 40 mm
position $z = 0$ mm

Sketch #2a



height = 1.7 mm
position $z = -1.7$ mm

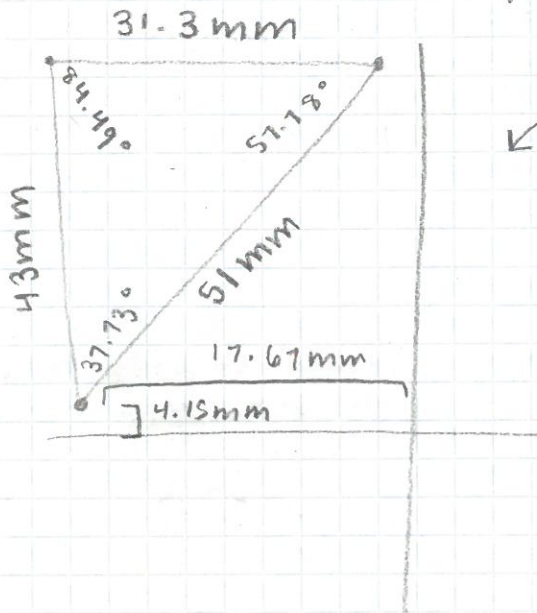
Sketch #3



height = 1.7 mm
position $z = -3.5$ mm

★ repeat sketch 2a (name this 2b.)
where height = 1.7mm and position z = -5.2mm
and repeat sketch 2a again (name this 2c)
where height = 4.8mm and position z = -10mm.

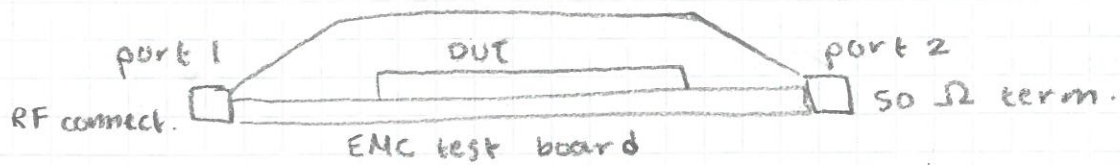
After sketching and padding is complete,
create a new sketch in the body
'Sketch #1'. Make this sketch a pocket to create
the angled surface



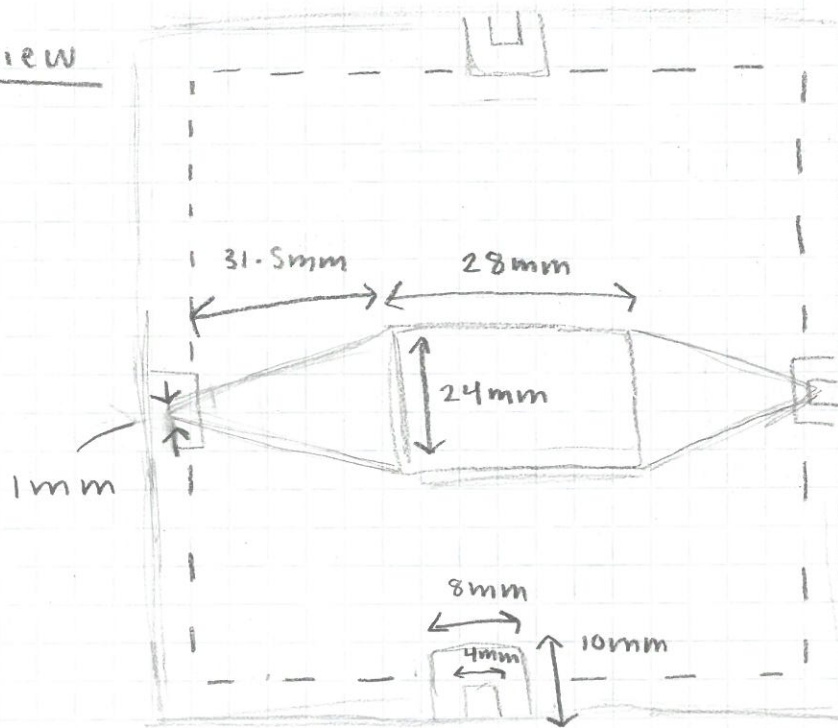
← create sketch in z4
plane with these
dimensions

Finally, round all outward, forward facing
edges by 1mm

IC - Stripline



top view



Layers of test board

Layer	Descript.	Material	Thickness
1	Signal	Copper	0.071 mm
		prepreg	0.152 mm
2	gnd	Copper	0.035 mm
		prepreg	1.028 mm
3	VCC	Copper	0.035 mm
		prepreg	0.152 mm
4	Signal	Copper	0.071 mm

specifications

frequency range - 150 kHz to 3 GHz

$$VSWR = 1.25$$

stripline height - the height of the dut must be less than 50% of the conductors height

stripline width - the width of the device under test must be less than 110% of the conductor width